

Bonding In Microsystem Technology

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Acknowledgments. List of Acronyms and Symbols. - 1. Introduction. - 2. Some remarks on microsystem systematic and development. 2.1 Literature- 3. Deep three-dimensional silicon micromachining. 3.1 Micromechanical substrates and mechanical properties of silicon. 3.2 Wet anisotropic etching of silicon. 3.3 Basic micromechanical constructions. 3.4 Literature- 4. Bonding. 4.1 Surface cleaning and activation. 4.2 High temperature fusion bonding. 4.3 Low temperature bonding. 4.4 Anodic (electrostatic) bonding. 4.5 Literature- 5. Classification of bonding and closing remarks. 5.1 Literature EAN/ISBN : 9781402045899 Publisher(s): Springer Netherlands Format: ePub/PDF Author(s): Dziuban, Jan A.

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